

Middle Power LED
3030

302L High Efficiency Series
Royal Blue

For Horticulture Lighting



LED 植物光源魔法师

Features & Benefits

- 1.0 W class middle power LED
- Mold resin for high reliability
- Standard form factor for design flexibility (3.0 × 3.0 mm)
- Radiant Efficiency @300mA: typ.50.6%
- The Highest PPE @300mA:2.0umol/s/w



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1. Characteristics

a) Absolute Maximum Rating

| Item | Symbol | Rating | Unit | Condition |
|---------------------------------|-----------|------------|---------|-----------------------------|
| Ambient / Operating Temperature | T_a | -40 ~ +105 | °C | - |
| Storage Temperature | T_{stg} | -40 ~ +105 | °C | - |
| LED Junction Temperature | T_j | 125 | °C | - |
| Forward Current | I_F | 300 | mA | - |
| Pulse Forward Current | I_{FP} | 1000 | mA | Duty 1/10, pulse width 10ms |
| Assembly Process Temperature | - | 260 <10 | °C s | - |
| ESD (HBM) | - | 2 | kV | - |

b) Electro-optical Characteristics ($I_F = 300 \text{ mA}$, $T_s = 25^\circ\text{C}$)

| Item | Unit | Rank | Min. | Typ. | Max. |
|--|--------|------|------|------|------|
| Forward Voltage (V_F) | V | V0 | 3.0 | 3.2 | 3.4 |
| Reverse Current(I_R) (@VR=5V) | μA | | - | - | 1 |
| Dominant wavelength (λ_D) | nm | UB0 | 445 | - | 465 |
| Peak wavelength (λ_P) | nm | | - | 455 | - |
| Photosynthetic Photon Flux(PPF) | μmol/s | | 1.60 | 1.80 | 2.00 |
| Radiant Power | mW | | 440 | 460 | 490 |
| Photosynthetic Active Radiation(PAR) | mW | | 438 | 458 | 488 |
| Thermal Resistance (junction to solder point) | °C/W | | - | 33 | - |
| Beam Angle | ° | | - | 120 | - |

Note:

Ledstar maintains measurement tolerance of: Radiant Power = $\pm 7\%$, forward voltage = $\pm 0.1 \text{ V}$, Wavelength = $\pm 2 \text{ nm}$

2. Product Code Information

| | | | | | | | | | | | | | | | | | | | | | | |
|---|---|---|---|---|---|---|---|---|----|----|----|----|----|----|----|----|----|----|----|----|---|---|
| 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 10 | 11 | 12 | 13 | 14 | 15 | 16 | 17 | 18 | 19 | 20 | 21 | | |
| L | D | R | - | 3 | 0 | 3 | 0 | T | T | A | B | 4 | 5 | 0 | - | V | 0 | U | B | 0 | P | 0 |

| Digit | PKG Information | Code | Specification |
|----------|--|---------------------------------|---|
| 1 2 3 | Ledstar Package Middle Power | LDR | |
| 4 5 6 7 | Package Model and Size | 3030 | 3.0 x 3.0 x 0.65mm |
| 8 | Product Category | T | Top View |
| 9 | Bractek Type | T | PCT & Cu |
| 10 | Version | A | |
| 11 | Color | B | Royal Blue |
| 12 13 14 | Wavelength Typical (nm) | 450 460 | 445~455 455~465 |
| 15 16 | Forward Voltage (V) | V0 | 3.0~3.4 Bin Code: G0 3.0~3.2 G1 3.0~3.1 G2 3.1~3.2 H0 3.2~3.4 H1 3.2~3.3 H2 3.3~3.4 |
| 17 18 19 | Dominant wavelength (nm) | UB0 UB1 UB2 UB3 UB4 | UB1 UB2 UB3 UB4 445~450 450~455 455~460 460~465 |
| 20 21 | Photosynthetic Photon Flux Efficiency (μmol/J) | P0 PA PB | PA PB 1.60~1.80 1.80~2.00 |

a) Voltage Bins ($I_F = 300 \text{ mA}$, $T_j = 25^\circ\text{C}$)

| Product Code | Voltage Rank | Voltage Bin | | Voltage Range (V) |
|-------------------------|--------------|-------------|----|-------------------|
| LDR-3030TTAB4*0-V0UB0P0 | V0 | G0 | G1 | 3.0 ~ 3.1 |
| | | | G2 | 3.1 ~ 3.2 |
| | | H0 | H1 | 3.2 ~ 3.3 |
| | | | H2 | 3.3 ~ 3.4 |

Note:

" * " can be "5", "6" of the wavelength

b) Wavelength Bins ($I_F = 300 \text{ mA}$, $T_j = 25^\circ\text{C}$)

| Product Code | Wavelength Rank | Wavelength Bin | | Wavelength Range (nm) |
|-------------------------|-----------------|----------------|--|-----------------------|
| LDR-3030TTAB450-V0UB0P0 | UB0 | UB1 | | 445 ~ 450 |
| | | UB2 | | 450 ~ 455 |
| LDR-3030TTAB460-V0UB0P0 | UB0 | UB3 | | 455 ~ 460 |
| | | UB4 | | 460 ~ 465 |

c) Luminous Flux Bins ($I_F = 300 \text{ mA}$, $T_j = 25^\circ\text{C}$)

| Product Code | Flux Rank | Flux Bin | Radiant Power Range (mW) | Flux Range (lm) |
|-------------------------|-----------|----------|--------------------------|-----------------|
| LDR-3030TTAB4*0-V0UB0P0 | P0 | PA | 440 ~ 490 | 1.6 ~ 1.8 |
| | | PB | 440 ~ 490 | 1.8 ~ 2.0 |

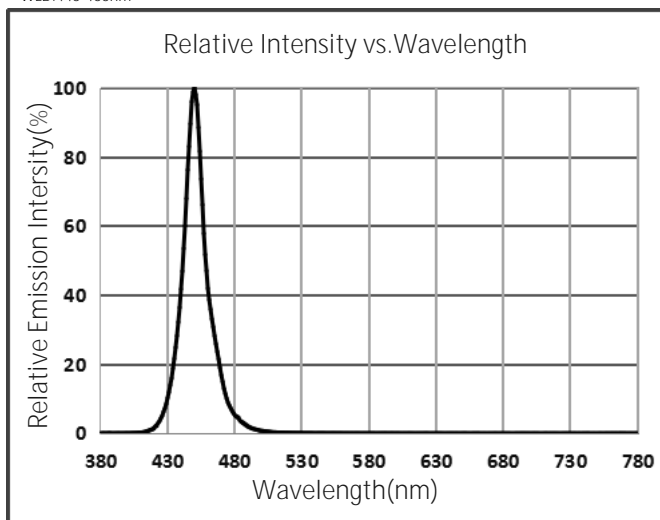
Note:

" * " can be "5", "6" of the wavelength

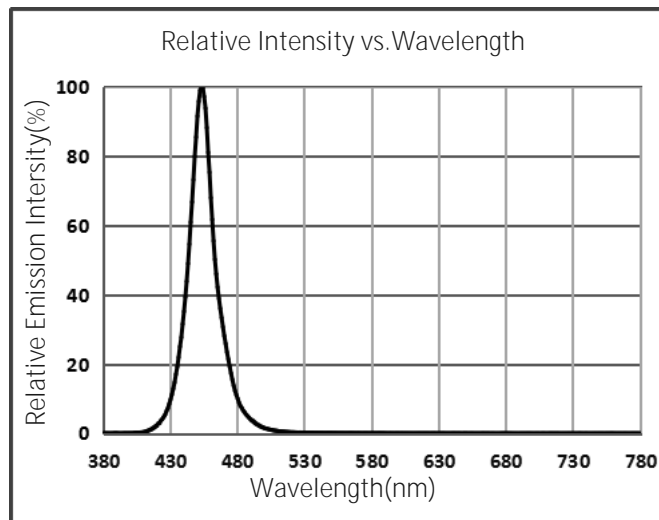
3. Typical Characteristics Graphs

a) Spectrum Distribution ($I_F = 300\text{ mA}$, $T_s = 25^\circ\text{C}$)

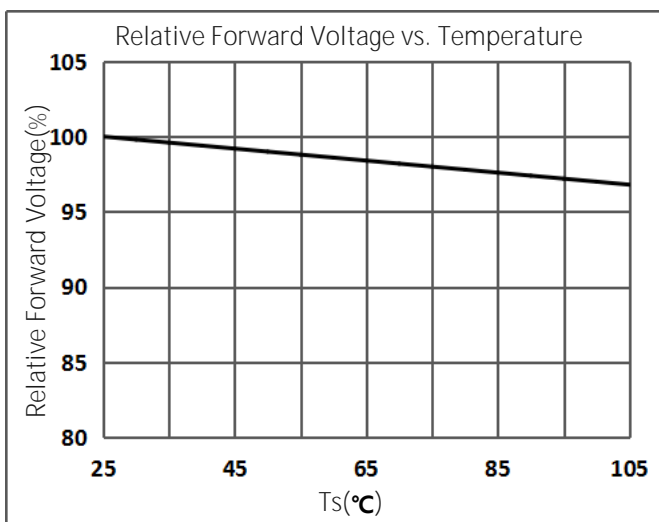
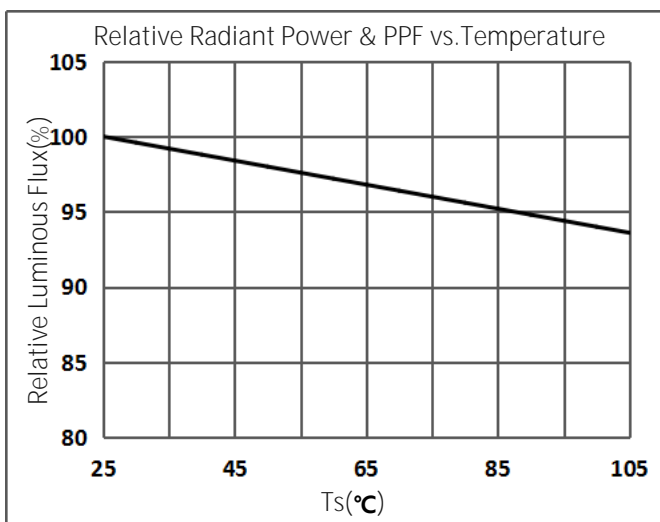
WLD:445-455nm



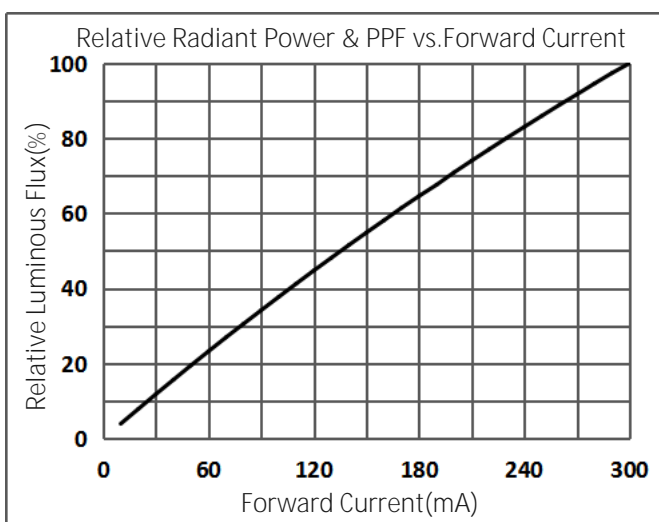
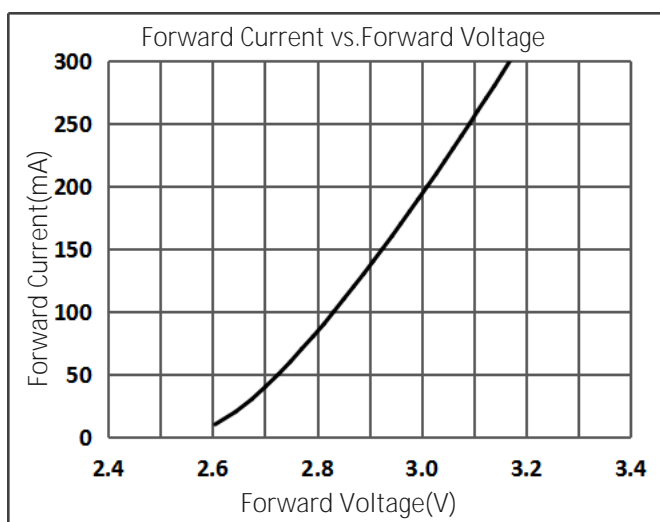
WLD:455-465nm

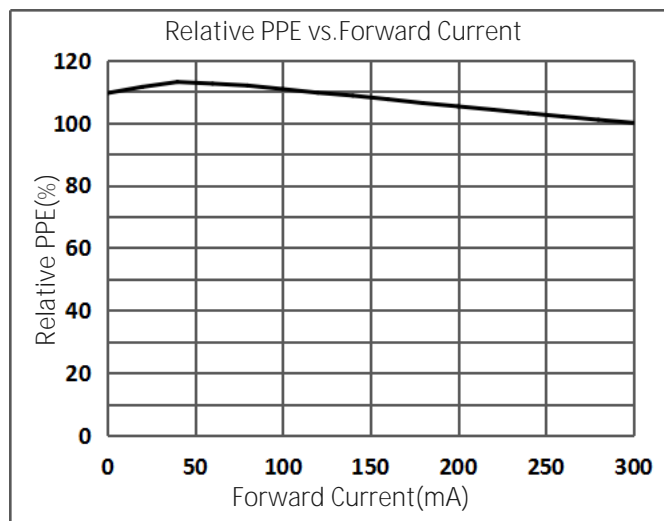


b) Temperature Characteristics ($I_F = 300\text{ mA}$)

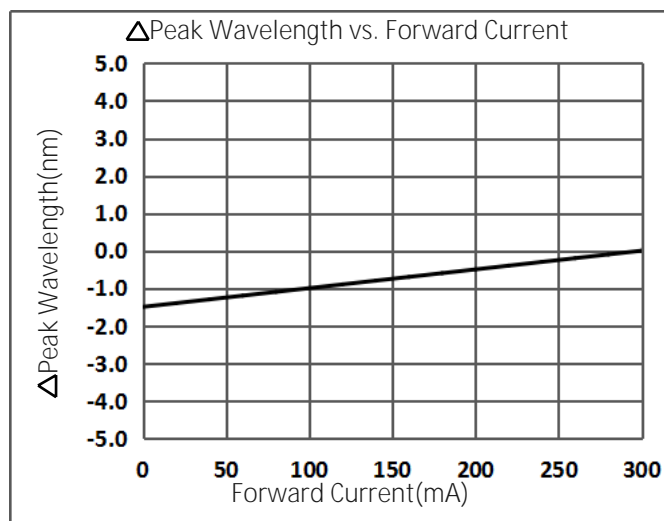


c) Forward Current Characteristics ($T_s = 25^\circ\text{C}$)

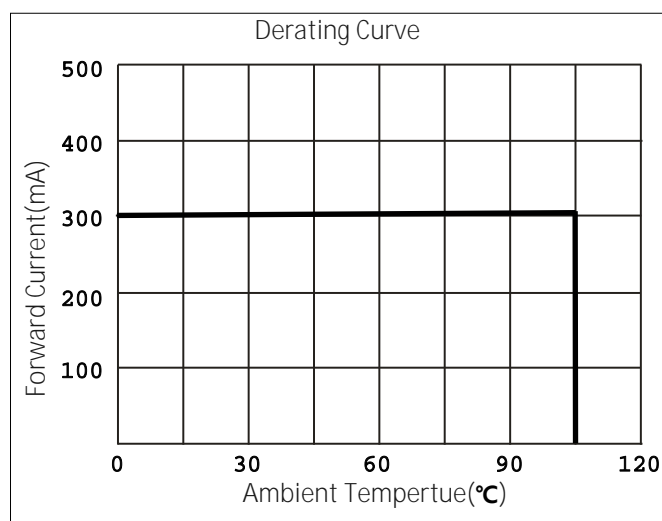




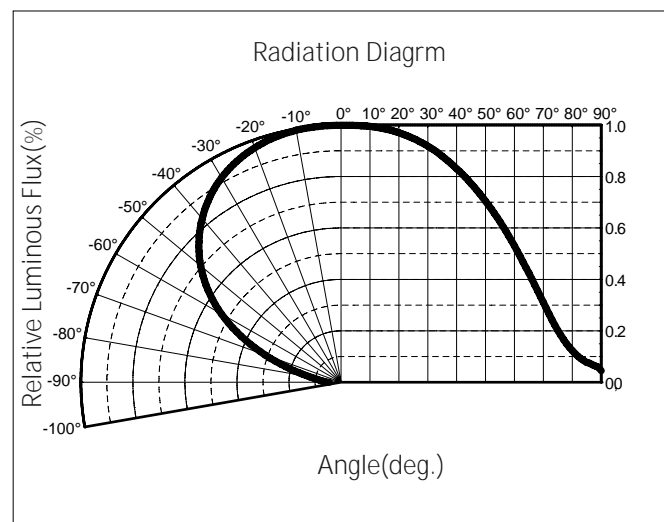
d) Color Shift Characteristics, $T_s = 25^\circ\text{C}$



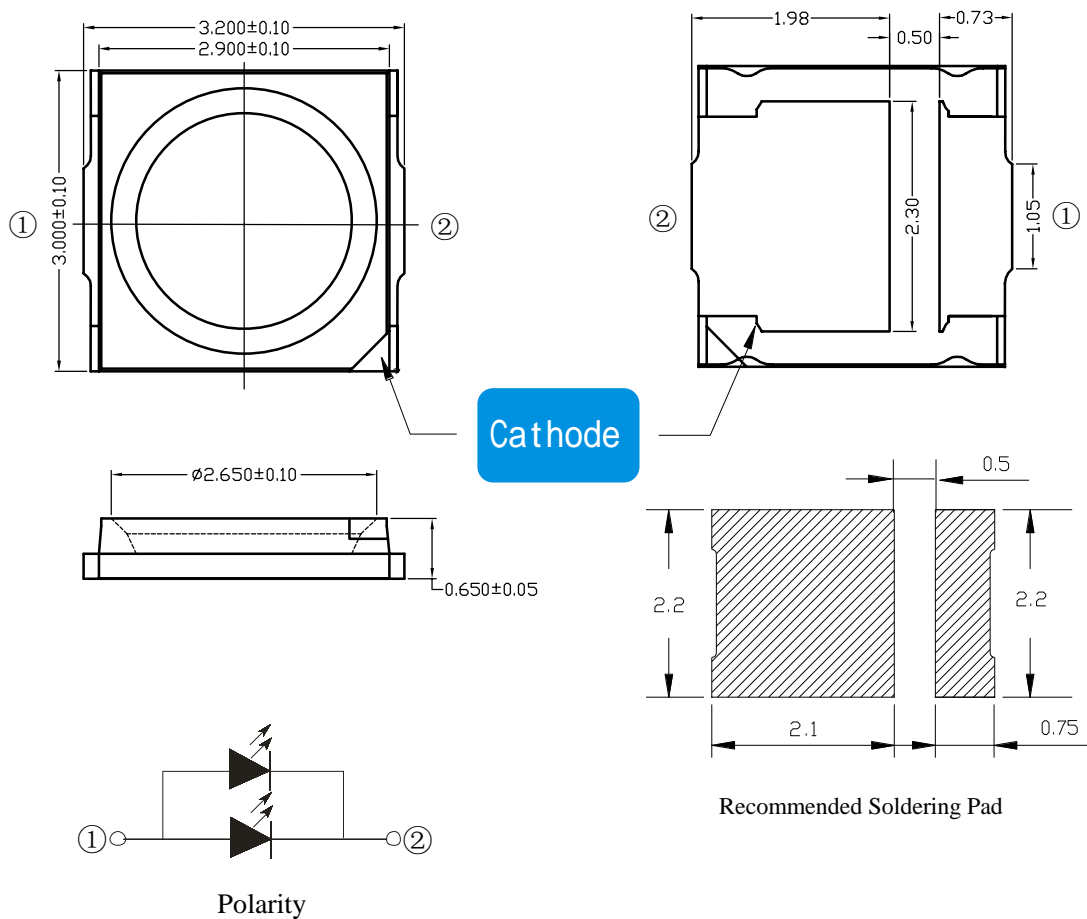
e) Derating Curve



f) Beam Angle Characteristics ($T_s = 25^\circ\text{C}$, $I_f = 300\text{ mA}$)



4. Outline Drawing & Dimension



Notes:

T_s point and measurement method:

- ① Measure one point at the cathode pad, if necessary remove PSR of PCB to reach T_s point.
- ② All pads must be soldered to the PCB to dissipate heat properly, otherwise the LED can be damaged.

Precautions:

- 1) Pressure on the LEDs will influence to the reliability of the LEDs. Precautions should be taken to avoid strong pressure on the LEDs. Do not put stress on the LEDs during heating.
- 2) Re-soldering should not be done after the LEDs have been soldered. If re-soldering is unavoidable, LED's characteristics should be carefully checked before and after such repair.
- 3) Do not stack assembled PCBs together. Since materials of LEDs is soft, abrasion between two PCB assembled with LED might cause catastrophic failure of the LEDs.

5. Reliability Test Items & Conditions

a) Test Items

| Test Item | Test Condition | Test Hour / Cycle | Sample No. |
|-------------------------------------|---|-------------------|------------|
| Room Temperature Life Test | 25°C, DC 300 mA | 1000 h | 22 |
| High Temperature Life Test | 85°C, DC 300 mA | 1000 h | 22 |
| High Temperature Humidity Life Test | 85°C, 85 % RH, DC 300 mA | 1000 h | 22 |
| Low Temperature Life Test | -40°C, DC 300 mA | 1000 h | 22 |
| Powered Temperature Cycle Test | -40 °C ~ 85°C, each 10 min, On/Off 5min , Temp. Change Time 20min, DC 300 mA | 100 cycles | 22 |
| Thermal Cycle | -40°C / 15 min ↔ 105°C / 15 min → Hot plate 180°C | 100 cycles | 100 |
| High Temperature Storage | 105°C | 1000 h | 22 |
| Low Temperature Storage | -40°C | 1000 h | 22 |

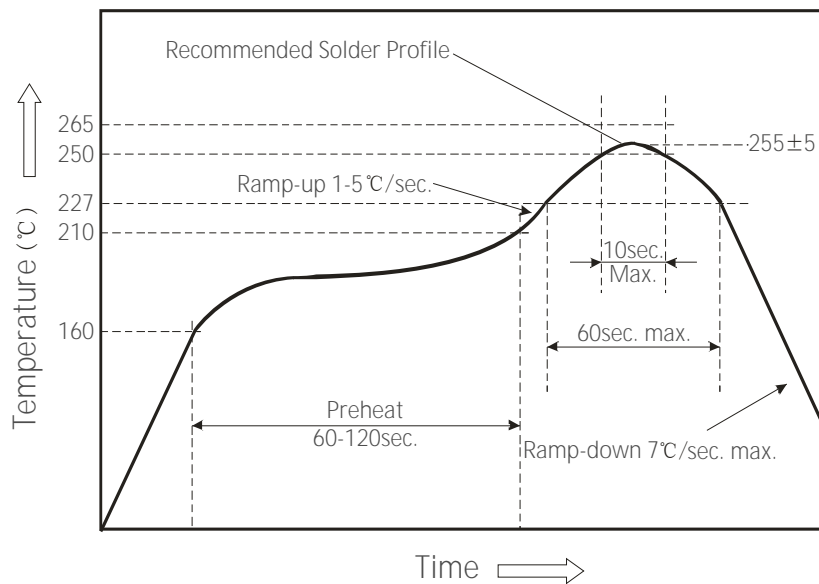
b) Criteria for Judging the Damage

| Item | Symbol | Test Condition (Ts = 25°C) | Limit | |
|-----------------|----------|-------------------------------|-------------------|-------------------|
| | | | Min | Max |
| Forward Voltage | V_F | $I_F = 300 \text{ mA}$ | Init. Value * 0.9 | Init. Value * 1.1 |
| Luminous Flux | Φ_v | $I_F = 300 \text{ mA}$ | Init. Value * 0.7 | Init. Value * 1.1 |

6. Soldering Conditions

a) Reflow Conditions (Pb free)

Reflow frequency: 2 times max.

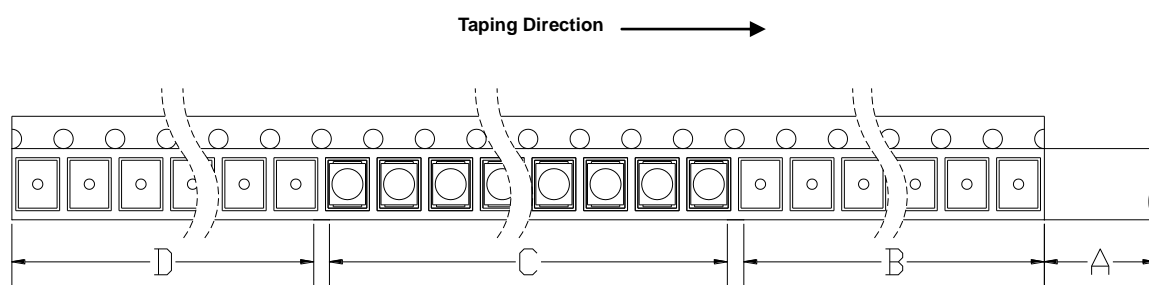
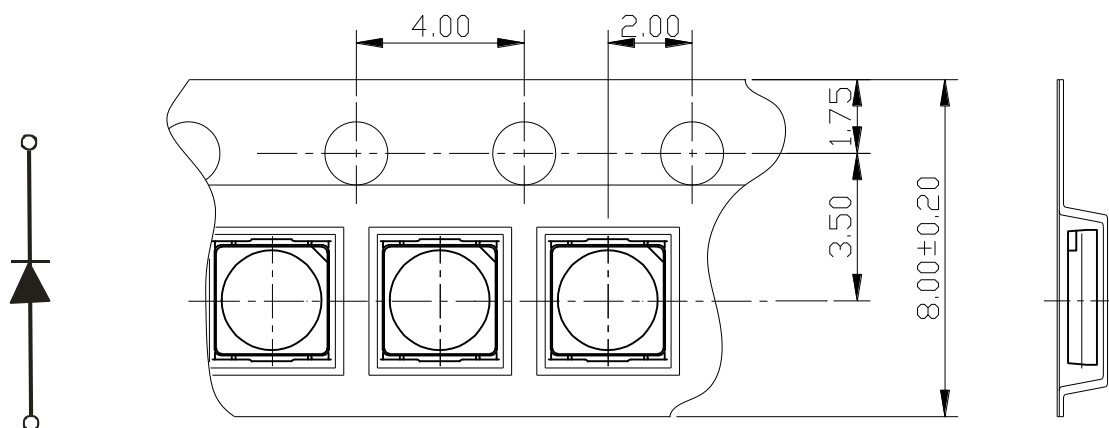


b) Manual Soldering Conditions

Not more than 5 seconds @ max. 300°C, under soldering iron.

7. Tape & Reel

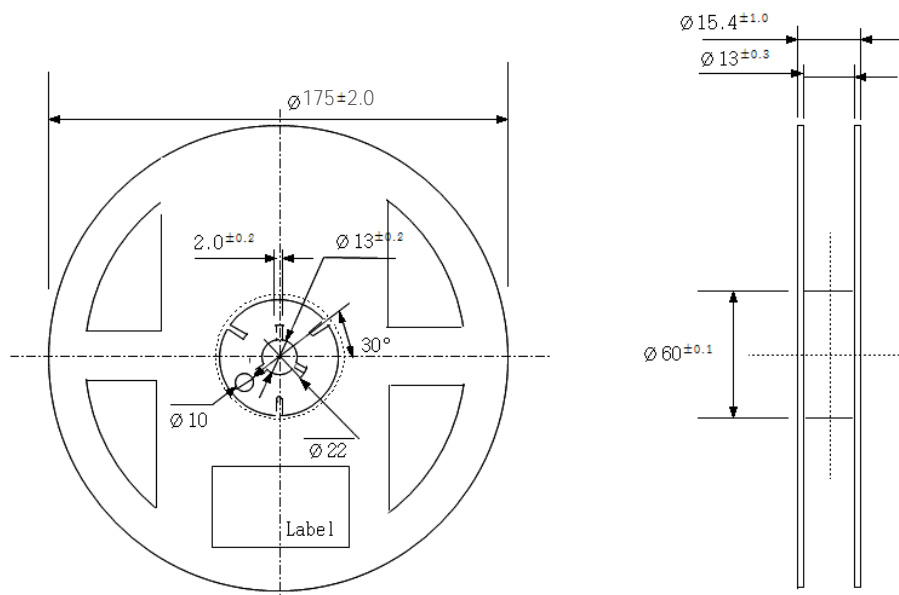
a) Taping Dimension



A: Top Cover Tape, 300mm; B: Leader, Empty, 200mm; C: 5000 Lamps Loaded; D: Trailer, Empty, 200mm.

b) Reel Dimension

(unit: mm)



Notes:

- 1) Quantity: The quantity/reel is 5,000 pcs
- 2) Cumulative Tolerance: Cumulative tolerance / 10 pitches is ± 0.2 mm
- 3) Adhesion Strength of Cover Tape: Adhesion strength is 0.1-0.7 N when the cover tape is turned off from the carrier tape at 10° angle to the carrier tape
- 4) Packaging: P/N, Manufacturing data code no. and quantity are indicated on the aluminum packing bag

8. Label Structure

a) Label Structure



Note: Denoted bin code and product code above is only an example (see description on page 5)

b) Label Explannation

Part No.:Product Code

IF:Testing Current

VF:Forward Voltage Range

PPE:Photosynthesis Photons Flux Efficiency Range

WLD(WLP):Wavelength Range

Date:Packing Date

Bin Code:Rank

C/N:Internal Identification Code

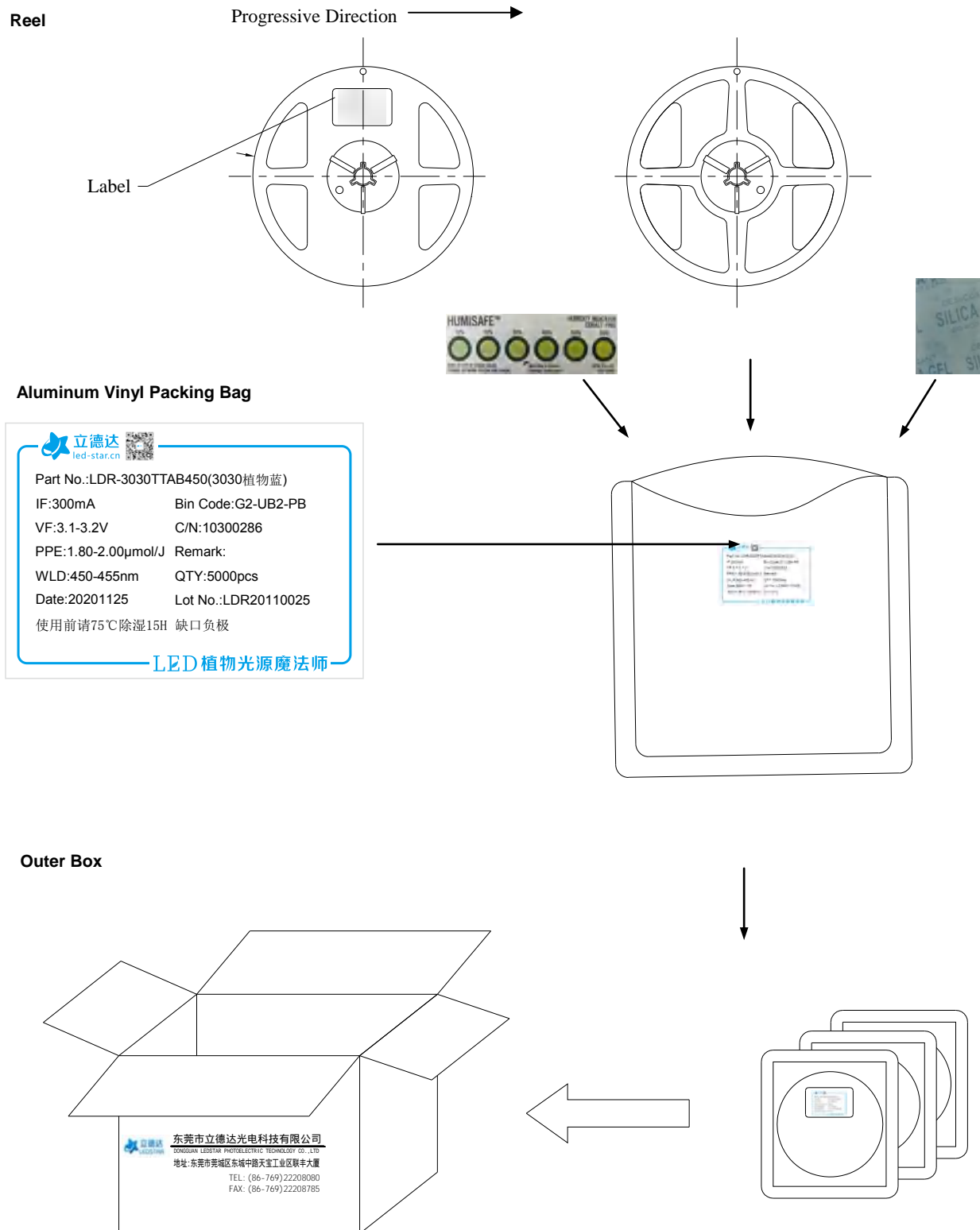
Remark:Special Remark

QTY:Quantity

Lot No.:Production batch Number

9. Packing Structure

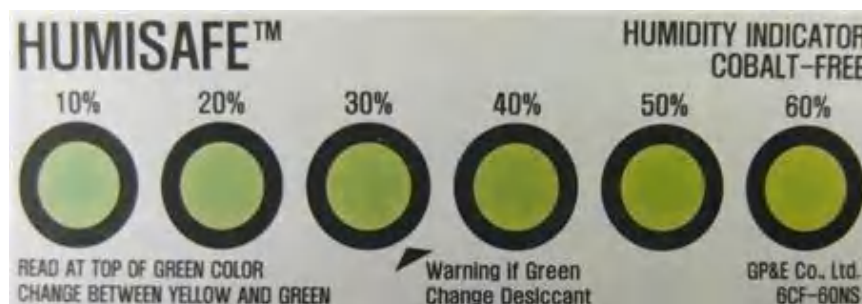
a) Packing Process (The quantity of PKG on the Reel to be Max 5,000pcs)



b) Aluminum Vinyl Packing Bag



c) Silica Gel & Humidity Indicator Card inside Aluminum Vinyl Bag



10. Precautions in Handling & Use

- 1) For over-current protection, users are recommended to apply resistors connected in series with the LEDs to mitigate sudden change of the forward current caused by shift of forward voltage.
- 2) This device should not be used in any type of fluid such as water, oil, organic solvent, etc. When cleaning is required, IPA is recommended as the cleaning agent. Some solvent-based cleaning agent may damage the silicone resins used in the device.
- 3) When the device is in operation, the forward current should be carefully determined considering the maximum ambient temperature and corresponding junction temperature.
- 4) LEDs must be stored in a clean environment. If the LEDs are to be stored for three months or more after being shipped from Ledstar, they should be packed with a nitrogen-filled container (shelf life of sealed bags is 12 months at temperature 0~40 °C, 0~90 % RH).
- 5) After storage bag is opened, device subjected to soldering, solder reflow, or other high temperature processes must be:
 - a. Mounted within 672 hours (28 days) at an assembly line with a condition of no more than 30 °C / 60 % RH^{*Note 1}, or
 - b. Mounted within 24 hours (1 day) at an assembly line with a condition of more than 30 °C / 70 % RH^{*Note 2}, or
 - c. Stored at <10 % RH.

*Note 1, 2: IPC/JEDEC J-STD-033A, Recommended Equivalent Total Floor Life Table

| Package Type and Body Thickness | Moisture Sensitivity Level | Maximum Percent Relative Humidity | | | | | | Temperature |
|---------------------------------|----------------------------|-----------------------------------|-----|-----|-----|-----|-----|-------------|
| | | 40% | 50% | 60% | 70% | 80% | 90% | |
| Body Thickness <2.1mm | Level 2a | ∞ | ∞ | 28 | 1 | 1 | 1 | 30°C |
| | | ∞ | ∞ | ∞ | 2 | 1 | 1 | 25°C |
| | | ∞ | ∞ | ∞ | 2 | 2 | 1 | 20°C |

- 6) Repack unused devices with anti-moisture packing, fold to close any opening and then store in a dry place.
- 7) Devices require baking before mounting, if humidity card reading is >60 % at 23 ± 5 °C.
- 8) Devices must be baked for 10~24 hours at 70 ± 5 °C, if baking is required.
- 9) The LEDs are sensitive to the static electricity and surge current. It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs. If voltage exceeding the absolute maximum rating is applied to LEDs, it may cause damage or even destruction to LED devices. Damaged LEDs may show some unusual characteristics such as increase in leakage current, lowered turn-on voltage, or abnormal lighting of LEDs at low current.
- 10) VOCs (Volatile Organic Compounds) can be generated from adhesives, flux, hardener or organic additives used in luminaires (fixtures). Transparent LED silicone encapsulant is permeable to those chemicals and they may lead to a discoloration of encapsulant when they exposed to heat or light. This phenomenon can cause a significant loss of light emitted (output) from the luminaires. In order to prevent these problems, we recommend users to know the physical properties of materials used in luminaires and they must be carefully selected.
- 11) Risk of sulfurization (or tarnishing)
 The LED from Ledstar uses a silver-plated lead frame and its surface color may change to black (or dark colored) when it is exposed to sulfur (S), chlorine (Cl) or other halogen compound. Sulfurization of lead frame may cause intensity degradation, change of chromaticity coordinates and, in extreme cases, open circuit. It requires caution. Due to possible sulfurization of lead frame, LED should not be used and stored together with oxidizing substances made of materials such as rubber, plain paper, lead solder cream, etc.